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TABLE OF CONTENTS

REFINED APPROACH ON CONTROLLING HEAT TRANSFER IN A VAPOUR PHASE SOLDERING OVEN	1
<i>Attila Géczy ; Balázs Péter Kiss ; Amine Mohamed Alaya ; Zsolt Illyefalvi-Vitéz</i>	
APPLICATION OF IRON MANGANITE THICK FILMS FOR HUMIDITY SENSING	6
<i>Maria Vesna Nikolic ; Miloljub D. Lukovic ; Milena Dojcinovic ; Zorka Z. Vasiljevic ; Nebojsa J. Labus</i>	
TOWARDS A SMART ELECTRONICS PRODUCTION USING MACHINE LEARNING TECHNIQUES	10
<i>Reinhardt Seidel ; Andreas Mayr ; Franziska Schäfer ; Dominik Kießkalt ; Jörg Franke</i>	
PROPERTIES OF THICK PRINTED COPPER FILMS ON ALUMINA SUBSTRATES	16
<i>Jiri Hlina ; Jan Reboun ; Ales Hamacek</i>	
ELECTRICAL PROPERTIES OF BIOPOLYMERS	21
<i>Henry Kettwig ; Daniel Frizlaff ; Patrick Otto ; Gunther Naumann ; Kathrin Harre ; Yvonne Joseph</i>	
SOLDERING OF SENSITIVE COMPONENTS BY SCREEN METHOD AND SURFACE MOUNTING	26
<i>Valentin Videkov ; Valentin Tsenev</i>	
THERMOCOUPLES, THERMOPILES AND THERMOELECTRIC GENERATORS ON RIGID AND FLEXIBLE SUBSTRATES	30
<i>Marta Turkiewicz ; Mirosław Gierczak ; Damian Nowak ; Piotr Markowski ; Eugeniusz Prociów ; Andrzej Dziedzic</i>	
THERMAL INVESTIGATIONS ON MODULES REALIZED USING SOLDERLESS ASSEMBLY FOR ELECTRONICS TECHNOLOGY	36
<i>Ciprian Ionescu ; Mihai Brânzei ; Norocel Codreanu ; Gaudentiu Varzaru</i>	
FULLY PRINTED IOT ANTENNA FOR DRONE-DEPLOYED AUTONOMOUS SENSOR UNIT	43
<i>Martin Pavec ; Jiri Navratil ; Radek Soukup ; Vaclav Smitka ; Ales Hamacek</i>	
DEVELOPMENT OF A NEW FABRICATION METHOD OF THERMOELECTRIC MICROGENERATORS	47
<i>Mirosław Gierczak ; Piotr Markowski ; Andrzej Dziedzic</i>	
MEASUREMENT OF GAS FLOW IN REFLOW OVEN	50
<i>Milan Hurban ; Ivan Szendiuch</i>	
OPTIMIZATIONS FOR HEAT DISSIPATION STRATEGIES ON PC MOTHERBOARDS	53
<i>Rajmond János ; Alexandra Fodor</i>	
TEMPERATURE DISTRIBUTION OPTIMIZATION FOR MULTICHANNEL SENSOR SYSTEM FOR THERMAL TESTING OF PROTECTIVE GLOVES	58
<i>David Kalas ; Karel Sima ; Silvan Pretl ; Jan Reboun ; Radek Soukup ; Ales Hamacek</i>	
COMBINATION OF THICK-FILM HYBRID TECHNOLOGY AND POLYMER ADDITIVE MANUFACTURING FOR HIGH-PERFORMANCE MECHATRONIC INTEGRATED DEVICES	63
<i>Thomas Ackstaller ; Lukas Lorenz ; Krzysztof Niewegłowski ; Karlheinz Bock</i>	
DEVELOPMENT OF SLID BONDING TECHNOLOGY FOR GAN ASSEMBLY BASED ON AG MICROFLAKES	69
<i>Marcin Mysliwiec ; Ryszard Kisiel</i>	
RELIABILITY OF GLUED JOINTS ON FLEXIBLE SUBSTRATES DURING ACCELERATED CURRENT AGEING	74
<i>Martin Hirman ; Jiri Navratil ; František Steiner ; Ales Hamacek</i>	
BEND TESTING OF SMD CHIP RESISTORS GLUED ON FLEXIBLE SUBSTRATES	81
<i>Martin Hirman ; Tomas Neuhöfer ; František Steiner</i>	
RESISTANCE WELDING IN SMART TEXTILE	87
<i>David Michal ; Stanislav Suchý ; Josef Šlauf ; Jan Reboun ; Radek Soukup</i>	
DOUBLE SIDED PRINTED PATTERN INTERCONNECTED BY AEROSOL JET AND NCA TECHNOLOGIES	93
<i>Jiri Navratil ; Tomas Rericha ; Vaclav Smitka ; Ales Hamacek</i>	
SUSTAINABLE AND SECURE SOLDERING OF COMPLEX COMPONENTS WITH PACKAGE BGA, LGA, FLIP CHIP, FI WLCSP, FO WLCSP TO STAR FLEX PCB USING HYBRID PRINTING	97
<i>Valentin Tsenev</i>	
PROCESS OPTIMIZATION OF FOIL-BASED TRANSIENT LIQUID PHASE BONDING FOR DIE ATTACHMENT	101
<i>Markus Feißt ; Jan Kustermann ; Axel Schumacher ; Irina Spies ; Jürgen Wilde</i>	

THE TESTING OF BRASS SOLDERABILITY FOR HYBRID SEWING THREAD.....	107
<i>Martin Pavec ; Martin Hirman ; Radek Soukup ; Ales Hamacek</i>	
WETTING OF DIFFERENT LEAD FREE SOLDER ALLOYS DURING VAPOUR PHASE SOLDERING.....	111
<i>Mohamed Amine Alaya ; László Gál ; Tamás Hurtony ; Bálint Medgyes ; Dániel Straubinger ; Al-Maaiteh Tareq I ; Balázs Illés ; Attila Géczy</i>	
RELIABILITY OF MOLDED INTERCONNECT DEVICES REGARDING CRACK INITIATION AND OVERMOLDING.....	117
<i>Philipp Braeuer ; Thomas Kuhn ; Martin Mueller ; Joerg Franke</i>	
THERMO-MECHANICAL TEST OF SNBI AND SNCU SOLDER JOINTS ON DIFFERENT SURFACE FINISHES.....	123
<i>David Bušek ; Karel Dušek ; Tomáš Beran ; Petr Veselý</i>	
STRESS CHARACTERIZATION OF CERAMIC SUBSTRATES BY LASER SPECKLE PHOTOMETRY.....	127
<i>Lili Chen ; Ulana Cikalova ; Stefan Muench ; Mike Roellig ; Beatrice Bendjus</i>	
RELEASED OF LATENT HEAT FROM SOLDER JOINTS TO SURROUNDING DURING SOLIDIFICATION OF SOLDER ALLOY - EXPERIMENTAL STUDY.....	133
<i>Karel Dušek ; Vít Zahradník ; Petr Veselý ; David Bušek ; Martin Placek</i>	
EARLY STAGE WHISKER DEVELOPMENT FROM SN THIN FILM ON CU SUBSTRATE.....	137
<i>Balázs Illés ; Tamás Hurtony ; Olivér Krammer ; Réka Bátorfi ; Bálint Medgyes ; Gábor Harsányi</i>	
APPLICATION POSSIBILITIES OF FUSED FILAMENT FABRICATION TECHNOLOGY FOR HIGH-VOLTAGE AND MEDIUM-VOLTAGE INSULATION SYSTEMS.....	142
<i>Tomáš Tichý ; Ondrej Šefl ; Petr Veselý ; Tomáš Cápál</i>	
EVALUATION OF BISMUTH/TIN SOLDER INTERMETALLIC LAYERS BASED ON HEATING FACTOR.....	148
<i>Petr Veselý ; Karel Dušek ; Angelika Stanková</i>	
MULTI-SENSOR HIGH-FREQUENCY EDDY CURRENT DEPTH DETECTION IN CARBON FIBER REINFORCED POLYMERS.....	154
<i>Marvieieva Nataliia ; Martin Schulze ; Lili Chen ; Iryna Patsora ; Henning Heuer</i>	
IMPACT OF WARPAGE EFFECTS ON QUALITY AND RELIABILITY OF SOLDER JOINTS.....	160
<i>Oliver Albrecht ; Heinz Wohlrabe ; Karsten Meier</i>	
MECHANICAL VS. ELECTRICAL PROPERTIES OF CONDUCTIVE ADHESIVE BONDS AS FUNCTION OF OPERATING TEMPERATURE.....	166
<i>Mihai Brânzei ; Paul Muşur Svasta ; Marian Vladescu ; Ioan Plotog ; Bogdan Mihailescu ; Gaudentiu Varzaru</i>	
IMPACT OF ATMOSPHERIC DISCHARGES ON THICK-FILMS ELECTRODES.....	173
<i>Tomasz Matusiak ; Arkadiusz Dabrowski ; Leszek Golonka</i>	
STUDY OF SOLDER SPREADABILITY AT DIFFERENT SOLDERING CONDITIONS USING FACTORIAL EXPERIMENTS.....	177
<i>Martin Molhanec</i>	
EVALUATION OF OXIDE THIN FILM LAYERS PREPARED BY SPUTTERING.....	181
<i>Eva Horynova ; Ivana Beshajova Pelikanova</i>	
COMPUTER CONTROLLED SYSTEM FOR IMPEDANCE MEASUREMENTS.....	186
<i>Ivaylo Zhivkov ; Rumén Yordanov ; Georgi Dobrikov ; Irena Yordanova ; Martin Weiter</i>	
NEW POSSIBLE WAY FOR BRAZING OF THICK FILM CERMET CONDUCTORS.....	191
<i>Alexandr Otáhal ; Josef Skácel ; Ivan Szendiuch</i>	
INFLUENCE OF ELECTRIC CURRENT AT SOLIDIFICATION OF SOLDER.....	196
<i>Josef Skácel ; Alexandr Otáhal ; Ivan Szendiuch</i>	
MANUFACTURING AND RELIABILITY ISSUES OF HIGHLY INTEGRATED PACKAGES FOR POWER ELECTRONIC APPLICATIONS.....	201
<i>Steffen Bickel ; Karsten Meier ; Mike Roellig ; Karlheinz Bock</i>	
CURRENT-CARRYING CAPACITY OF THICK-FILM METALLIZATION PATHS.....	207
<i>Arkadiusz Dabrowski ; Radoslaw Wilkosz</i>	
LARGE AREA TEMPERATURE MEASUREMENT IN SMART TEXTILES.....	213
<i>Jan Kalcik ; Radek Soukup</i>	
RELATIONSHIP OF SOLDERING PROFILE, VOIDS FORMATION AND STRENGTH OF SOLDERED JOINTS.....	217
<i>František Steiner ; Václav Wirth ; Martin Hirman</i>	
EFFECT OF PCB THICKNESS AND HEIGHT POSITION DURING HEAT LEVEL TYPE VAPOUR PHASE REFLOW SOLDERING.....	223
<i>Mohamed Amine Alaya ; Attila Géczy</i>	

PARTICLE LEVEL MODELLING OF SOLDER PASTES RHEOLOGICAL BEHAVIOUR IN VISCOSITY MEASUREMENT	229
<i>Tareq Al-Ma'Aiteh ; Olivér Krammer</i>	
CURRENT MODE CONTROL OF A SOLAR INVERTER WITH MPPT ALGORITHM	235
<i>Izsák Ferencz ; Dorin Petreus</i>	
INVESTIGATING THE EFFECT OF VISCOSITY MODELS ON THE STENCIL PRINTING BY NUMERICAL MODELLING	242
<i>Oliver Krammér ; Tareq Al-Ma'Aiteh ; Peter Martinek</i>	
ANALYTICAL CONSIDERATIONS OF THE TRL CALIBRATION PROCEDURE FOR GENERAL DE-EMBEDDING PURPOSES	248
<i>Ulrich Schumann ; Andreas Jöstingmeier ; Abbas Omar</i>	
FREQUENCY INDEPENDENT LUMPED PARAMETER MODEL OF FERRITE CORE	252
<i>Miodrag Milutinov ; Ljiljana Živanov ; Nelu Blaž</i>	
ANALYTICAL SOLUTION OF HEAT DISTRIBUTION INSIDE A PRINTED CIRCUIT BOARD DURING VAPOUR PHASE SOLDERING	256
<i>Dániel Straubinger ; István Bozsóki ; Balázs Illés ; Attila Géczy</i>	
MEASURING COMPONENT SELF-ALIGNMENT BY AUTOMATIC IMAGE PROCESSING METHOD	261
<i>Peter Martinek ; Balazs Villanyi ; Olivér Krammer</i>	
DESIGN OF MICROSTRIP ANTENNAS FOR 2.45 GHZ ON DIFFERENT SUBSTRATES	266
<i>Peter Cech ; Alena Pietriková</i>	
3D THERMAL MODELLING AND VERIFICATION OF POWER ELECTRONIC MODULES	272
<i>Nikolay Vakrilov ; Anna Stoynova ; Borislav Bonev</i>	
RESEARCH OF ACCELERATION AND BRAKING MODES OF ELECTRIC VEHICLES IN MATLAB/SIMULINK	276
<i>Gergana Vacheva ; Nikolay Hinov ; Vladimir Dimitrov</i>	
THERMAL MODELLING AND SIMULATION TECHNIQUES FOR MULTICORE PROCESSORS	281
<i>Alexandra Fodor ; Gabriel Chindris ; Rajmond Jánó ; Dan Pitica</i>	
REAL-TIME SYSTEM WITH INTEGRATED PID ALGORITHM USED FOR DC MOTOR CONTROL	286
<i>Marius Alexandru Taut ; Gabriel Chindris ; Dan Pitica</i>	
LOSS FACTOR AND NON-LINEARITY OF VOLT-AMPERE CHARACTERISTIC OF CAPACITORS FROM METALIZED PP FILM	292
<i>Pavel Mach ; Martin Horák</i>	
INFLUENCE OF TEMPERATURE SHOCKS ON CLIMATIC AGING OF CONDUCTIVE ADHESIVE JOINTS	297
<i>Ferdinand Závora ; Pavel Mach</i>	
METHODS FOR REUSING LI-ION CELLS FROM DISCARDED BATTERY PACKS	301
<i>Adelina Ioana Ilies ; Ioan Ciascai ; Dan Pitica</i>	
USABILITY OF BIO-BASED POLYMERS FOR PCB	307
<i>Carolin Henning ; Anna Schmid ; Sophia Hecht ; Cindy Rückmar ; Kathrin Harre ; Reinhard Bauer</i>	
COST OPTIMIZATION AND DAY-AHEAD SCHEDULING FOR A RENEWABLE ENERGY MICROGRID	313
<i>Andreea Ignat ; Dorin Petreus ; Eniko Lazar</i>	
SHEET RESISTANCE MEASUREMENT OF INKJET PRINTED LAYERS	319
<i>Elitsa Gieva ; Georgi Nikolov ; Boyanka Nikolova</i>	
MEASUREMENT OF THERMAL PROPERTIES AND INTERFACE THERMAL RESISTANCE OF THIN FILMS BY THERMOREFLECTANCE	325
<i>Elie Badine ; Mathieu Bardoux ; Nadine Abboud ; Abdelhak Hadj Sahraoui ; Ziad Herro</i>	
WHITE LIGHT AC ELECTROLUMINESCENT DISPLAYS	331
<i>Michal Hrabal ; Ivaylo Zhivkov ; Patricia Guricova ; Georgi Dobrikov ; Rumen Yordanov ; Martin Vala</i>	
DEFECTS INVESTIGATION IN LOW-TEMPERATURE AND LOW-PRESSURE SINTERED SILVER THERMAL JOINTS FOR NON-METALIZED SEMICONDUCTORS	336
<i>Krzysztof Stojek ; Jan Felba ; Danylo Lizanets ; Milena Kiliszkievicz ; Tomasz Falat ; Kamil Gorzka</i>	
WIRELESS SENSOR NODES OPTIMIZED FOR INDUSTRIAL SOLDERING EQUIPMENT	342
<i>Arne Neiser ; Melanie Abb ; Dirk Seehase ; Andreas Reinhardt</i>	
COPLANAR CAPACITIVE LIQUID LEVEL SENSOR	346
<i>Alena Pietriková ; Samuel Zuk ; Igor Vehec</i>	
ELECTRONIC SENSOR SYSTEM FOR MONITORING THE TEMPERATURE STATUS OF ROLLING STOCK IN MOTION	352
<i>Anna Stoynova ; Nencho Nenov ; Borislav Bonev ; Desislava Yosifova</i>	

APPLICATION OF STRETCHABLE MEMBRANE WITH FERRITE FLAKY FILLERS IN INDUCTIVE DISPLACEMENT SENSOR.....	358
<i>Nelu Blaž ; Milica Kisić ; Ljiljana Živanov ; Cedo Žlebić ; Stanko Aleksić ; Mirjana Damnjanović</i>	
UNIAXIAL HEAT LOSS ANEMOMETER IN POWER SAVE REGIME.....	363
<i>Stanko O. Aleksić ; Nebojša S. Mitrović ; Miloljub D. Luković ; Nelu Blaž ; Snezana G. Luković ; Ljiljana D. Živanov</i>	
OPTIMIZATION OF CRYOGENIC DEEP REACTIVE ION ETCHING PROCESS FOR ON-CHIP ENERGY STORAGE.....	368
<i>Jan Prášek ; David Houška ; Radim Hrdý ; Jaromír Hubálek ; Ulrich Schmid</i>	
DATA ACQUISITION SYSTEM FOR SOLAR PANELS.....	374
<i>Vladimír Voicu ; Dorin Petreus ; Radu Ețz</i>	
CAPACITIVE FORCE SENSOR FABRICATED IN ADDITIVE TECHNOLOGY	380
<i>Milica Kisić ; Nelu Blaž ; Ljiljana Živanov ; Mirjana Damnjanović</i>	
DEVELOPMENT OF HFO₂/AL₂O₃ STACK FOR ON-CHIP CAPACITOR APPLICATIONS.....	385
<i>Radim Hrdý ; Jan Prášek ; Patrik Fillner ; Silvestr Vancík ; Michael Schneider ; Jaromír Hubálek ; Ulrich Schmid</i>	
LTCC-BASED MICROFLUIDIC MODULE FOR HEATING AND DETECTION OF FLUIDS USING MICROWAVES.....	389
<i>Laura Jasinska ; Karol Malecha ; Wojciech Wróblewski</i>	
APPLICATION OF NEURAL NETWORK FOR SMART CONTROL OF A BUCK DC/DC CONVERTER.....	394
<i>Gergana Vacheva ; Nikolay Hinov ; Hristiyan Kanchev ; Bogdan Gilev</i>	
MODELLING OF DC/DC BIDIRECTIONAL CONVERTER FOR ELECTRIC VEHICLES APPLICATION	398
<i>Gergana Vacheva ; Nikolay Hinov ; Vladimir Dimitrov</i>	
PLANAR RESONANCE CIRCUITS FOR IDENTITY DOCUMENTS OR BANKNOTES AUTHENTICATION.....	403
<i>Tomas Blecha ; Jiri Cengery ; Silvan Pretl ; Vaclav Smitka</i>	
RESEARCH OF THE PHOTOCAPACITOR EFFECT IN A₂B₆ MONOCRYSTALS	407
<i>Ostap Oliinyk ; Oleksii Tsybul'skyi ; Viktor Sergiychuk ; Borys Tsyganok</i>	
3D MICRO-TRANSFORMERS FABRICATED INSIDE FERRITE-DIELECTRIC LTCC SUBSTRATE	409
<i>Andrea Maric ; Ljiljana Živanov</i>	
AC COUPLED INSTRUMENTATION AMPLIFIER WITH GYRATORS	414
<i>Mihai Alexandru Ilie ; Elena-Mirela Stetco ; Liviu Viman ; Dan Pitița</i>	
TUNING THE INDUCTANCE OF MAGNETIC INDUCTOR WITH DC CURRENT.....	419
<i>Cedo Žlebić ; Ljiljana Živanov ; Nelu Blaž ; Mirjana Damnjanović</i>	
Author Index	